



Connectors > Socket Connectors > IC Sockets > LGA Sockets > LGA 2011 Sockets



IC Socket Type: **LGA 2011**

Connector System: **Board-to-Board**

Number of Positions: **2011**

Contact Mating Area Plating Material Thickness: **[30 μin]**

Centerline (Pitch): **1.02 mm [.04 in]**

Features

Product Type Features

Connector System	Board-to-Board
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Number of Positions	2011
Grid Spacing	1.016 x .8814 mm [.040 x .0347 in]

Body Features

Frame Style	Square
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Contact Features

Contact Mating Area Plating Material	Gold
Contact Base Material	Copper Alloy
IC Socket Type	LGA 2011
	30 μin
Contact Current Rating (Max)	.5 A

Termination Features

Termination Method to Printed Circuit Board	Surface Mount - Solder Ball
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Mechanical Attachment

Connector Mounting Type	Board Mount
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Housing Features

Housing Material	High Temperature Thermoplastic
Housing Color	Black
Centerline (Pitch)	1.02 mm[.04 in]

Usage Conditions

Operating Temperature Range	-25 – 100 °C[-13 – 212 °F]
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Operation/Application

Circuit Application	Signal
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Tray Color	Blue
Packaging Method	Tray

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

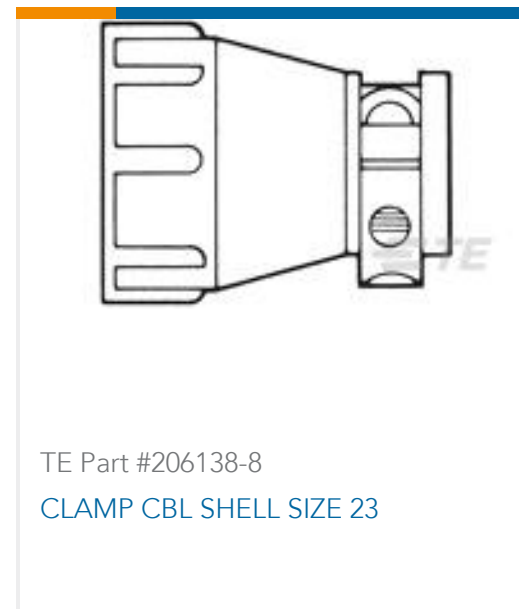
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products

will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

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Customer View Model

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Product Specifications

Product Specification

English